

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0736420000

Status:

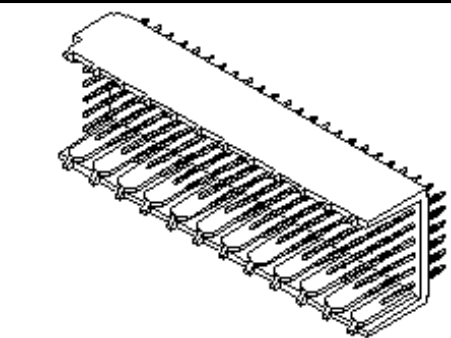
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits



Series
image - Reference only

Documents:

- [3D Model](#)
- [Test Summary \(PDF\)](#)
- [Drawing \(PDF\)](#)
- [Product Specification PS-73670-9999 \(PDF\)](#)
- [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

UL

LR19980

E29179

General

Product Family

Series

Application

Comments

Component Type

Overview

Product Name

Style

Backplane Connectors

73642

Backplane

Standard Press-Fit

PCB Header

[hdm](#)

HDM®

N/A

Physical

Circuits (Loaded)

Circuits (maximum)

Color - Resin

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Material - Metal

Material - Plating Mating

Material - Plating Termination

Material - Resin

Number of Columns

Number of Pairs

Number of Rows

Orientation

PC Tail Length (in)

PC Tail Length (mm)

PCB Locator

PCB Retention

PCB Thickness Recommended (in)

PCB Thickness Recommended (mm)

Packaging Type

Pitch - Mating Interface (in)

Pitch - Mating Interface (mm)

Pitch - Term. Interface (in)

Pitch - Term. Interface (mm)

Plating min: Mating (µin)

Plating min: Mating (µm)

Plating min: Termination (µin)

72

72

Black, Natural

250

No

94V-0

No

None

Phosphor Bronze

Gold

Gold

High Temperature Thermoplastic

12

Open Pin Field

6

Vertical

0.138 In

3.50 mm

No

Yes

0.062 In

1.60 mm

Tube

0.079 In

2.00 mm

0.079 In

2.00 mm

30

0.75

2

EU RoHS

ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



Need more information on product
environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

73642Series

Mates With

73632 HDM PLUS® Board-to-Board
Daughtercard Receptacle. 73780 HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.

Global

Description	Product #
Flat Rock Tooling for Pneumatic Press	0622013700
HDM® Backplane Insertion Signal Contact Tool	0621001400
Extraction Tool	0621001000

Plating min: Termination (μm)	0.05
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SDA-73642-****

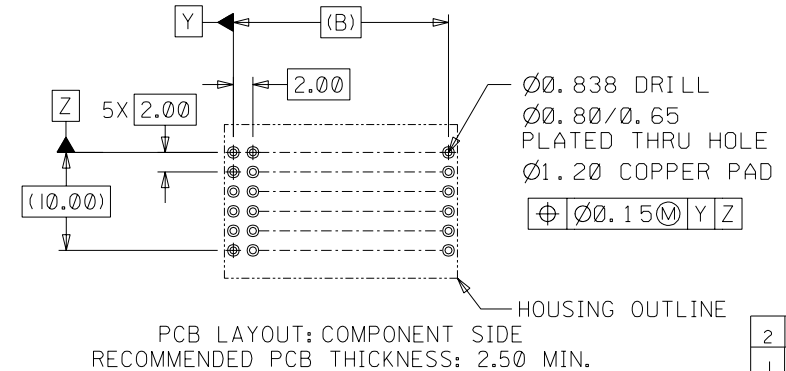
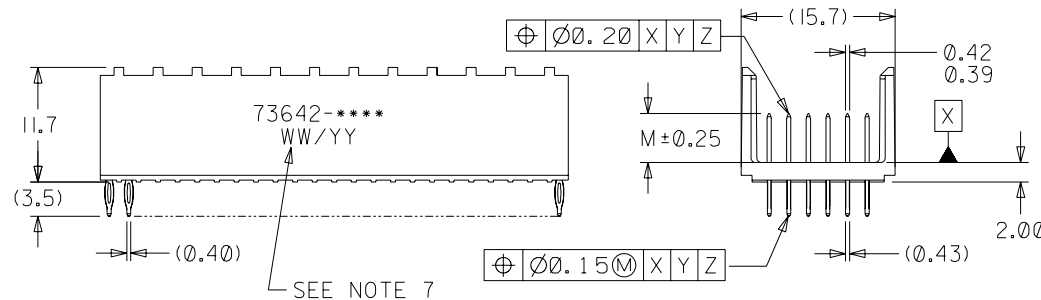
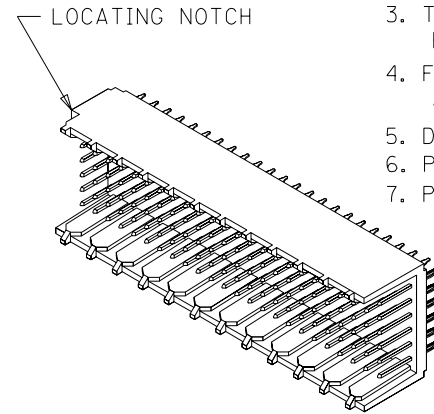
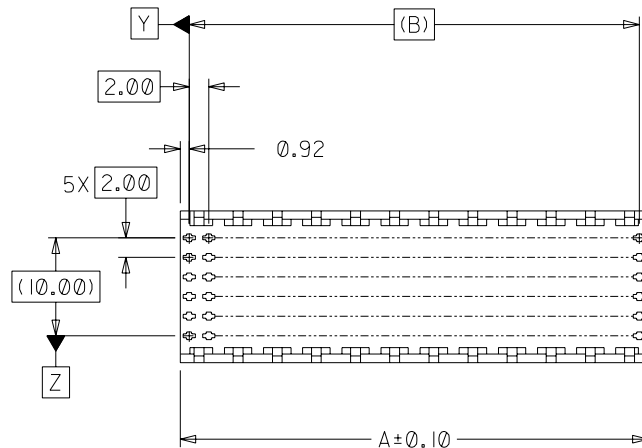
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This document was generated on 05/14/2010

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NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; SELECTIVE TIN/LEAD (Sn/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



2	C
I	I
SH	REV

I	REVISED ECR UCP2003-2260 THOMAS 03/04/25	F	REVISED ECR UDT1999-0476 BINGHAM 98/12/21	C	REVISED PER ECR #U81357 BINGHAM 97/12/15
H	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	E	REVISED ECR UDT1999-0243 BINGHAM 98/09/29	B	REVISED PER ECR #U70950 BINGHAM 97/02/14
G	REVISED ECR UDT1999-0662 BINGHAM 99/05/18	D	REVISED ECR UDT1998-0240 BINGHAM 98/05/06	A	RELEASED FOR PROD. PER ECR # U70371 BINGHAM 96/12/18
LTR.	REVISIONS	LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE	INCH METRIC
2 PLACE	± N/A ± 0.05
1 PLACE	--- ± 0.10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
DRWG. BY: JRR	CHK'D. BY: SMR
APP'D. BY: CAB	SCALE 2 : 1

▽ = 0 ▼ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION			
MOLEX INCORPORATED LITSE,ILL. 60532 U.S.A.		SHEET NO. 1 OF 2	DATE 96/12/18
PART NO. SEE SHEET 2		DRWG. NO. SDA-73642-****	
FILE NAME S73642X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
DIV. DA		SIZE B	

	10	9	8	7	6	5	4	3	2	1	73642
F											
E											
D											
C											
B											
A											

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73642-0000	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.00
73642-0100	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.50
73642-0200	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	6.00
73642-1000	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.00
73642-1100	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.50
73642-1200	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	6.00
73642-2000	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.00
73642-2100	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.50
73642-2200	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	6.00
73642-3000	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.00
73642-3100	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.50
73642-3200	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	6.00

		C	SEE SHEET I
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH			
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°			
INCH		METRIC	
3 PLACE	± N/A	---	
2 PLACE	± N/A	± 0.05	
1 PLACE	---	± 0.10	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	NO*NE

▽ = 0 ▼ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION			
molex MOLEX INCORPORATED LISLE,ILL. 60532 U.S.A.		SHEET NO. 2	DATE 97/12/15
PART NO. SEE CHART		DRWG. NO. SDA-73642-*****	
FILE NAME S73642X2 DGN		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
DIV. DA		SIZE B	

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<http://moschip.ru/get-element>

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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